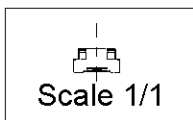
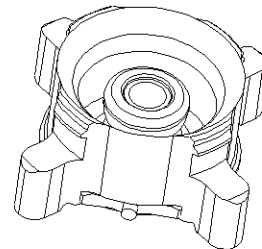
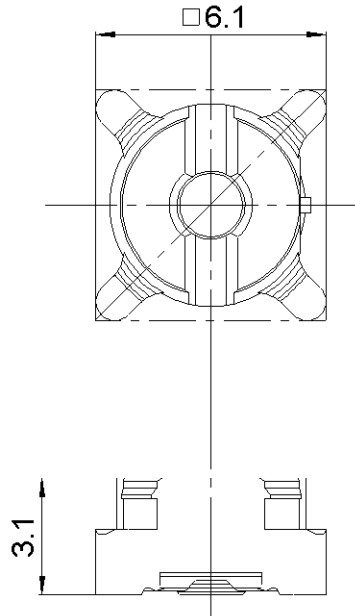


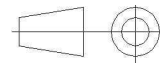
SMTJACK RECEPTACLE

R223.424.000

Series : MMBX



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
BODY	BRASS	NPGR
CENTER CONTACT	BRASS	NPGR
OUTER CONTACT	-	-
INSULATOR	LIQUID CRYSTAL POLYMER	
GASKET	-	
OTHERS PARTS	-	
-	-	
-	-	

Issue : 0736 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



SMTJACK RECEPTACLE

R223.424.000

Series : MMBX

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance		50 Ω
Frequency		0-12.4 GHz
VSWR	1.065 +	0,0000 x F(GHz) Maxi
Insertion loss		0.12 √F(GHz) dB Maxi
RF leakage	- (100 - F(GHz)) dB Maxi
Voltage rating		330 Veff Maxi
Dielectric withstanding voltage		1000 Veff mini
Insulation resistance		1000 MΩ mini

Operating temperature	-55/+155 ° C
Hermetic seal	NA Atm.cm3/s
Panel leakage	NA

OTHER CHARACTERISTICS

Assembly instruction **NA**

Others :
to 6 GHz
Interface MMBX only, up to 2.5 GHz
PCB to PCB -45dB up to 2.5 GHz

Mated pair height 6.7mm

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	10	N mini
Axial force – Opposite end	10	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	100	Cycles mini
Weight	0,3050	g

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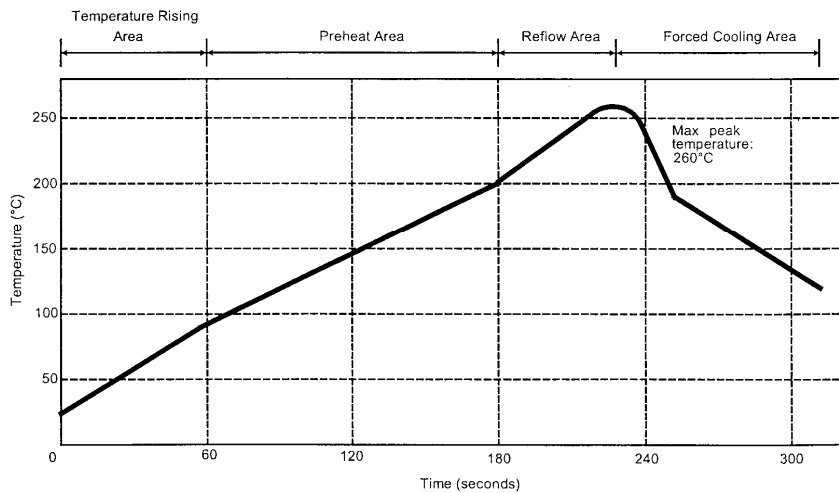
**SOLDER PROCEDURE OF MMBX RECEPTACLE
IN INDUSTRIAL ENVIRONMENT**

1. Deposit solder paste ‘SnAg4Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type.

A video camera is recommended for positioning of the component.

Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven.
Below please find, the typical profile to use.
4. The cleaning of printed circuit boards is not obliged.
5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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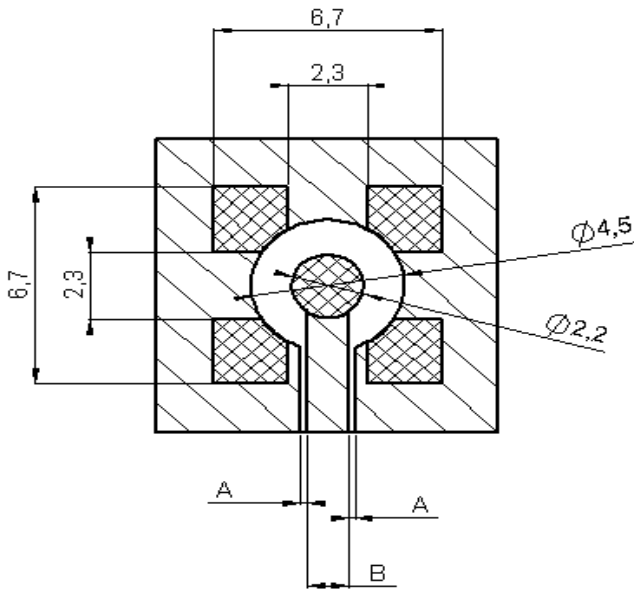
SMTJACK RECEPTACLE

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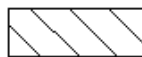
MMBX SERIES INFORMATIONS

PCB



COPLANAR LINE

Pattern and signal are on the same side
 The material of PCB is epoxy resin (FR4).
 (Er = 4.6)
 The solder resist should be printed
 Except for the land pattern on the PCB



Pattern



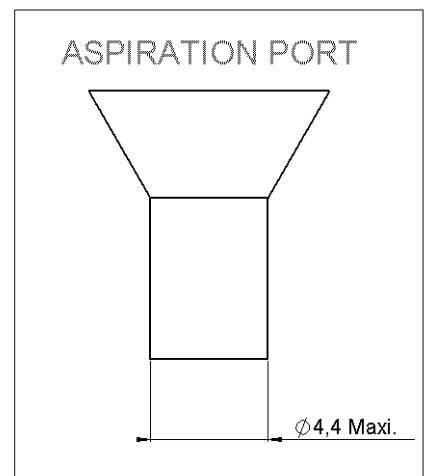
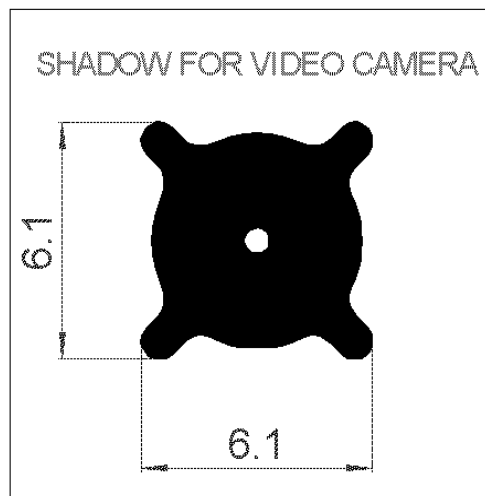
Land for solder paste

**APPLICATION 75Ω
 WITH B = 0,55mm**

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1,6	0,375

**APPLICATION 50Ω
 WITH B = 1,2mm**

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
1,6	0,210



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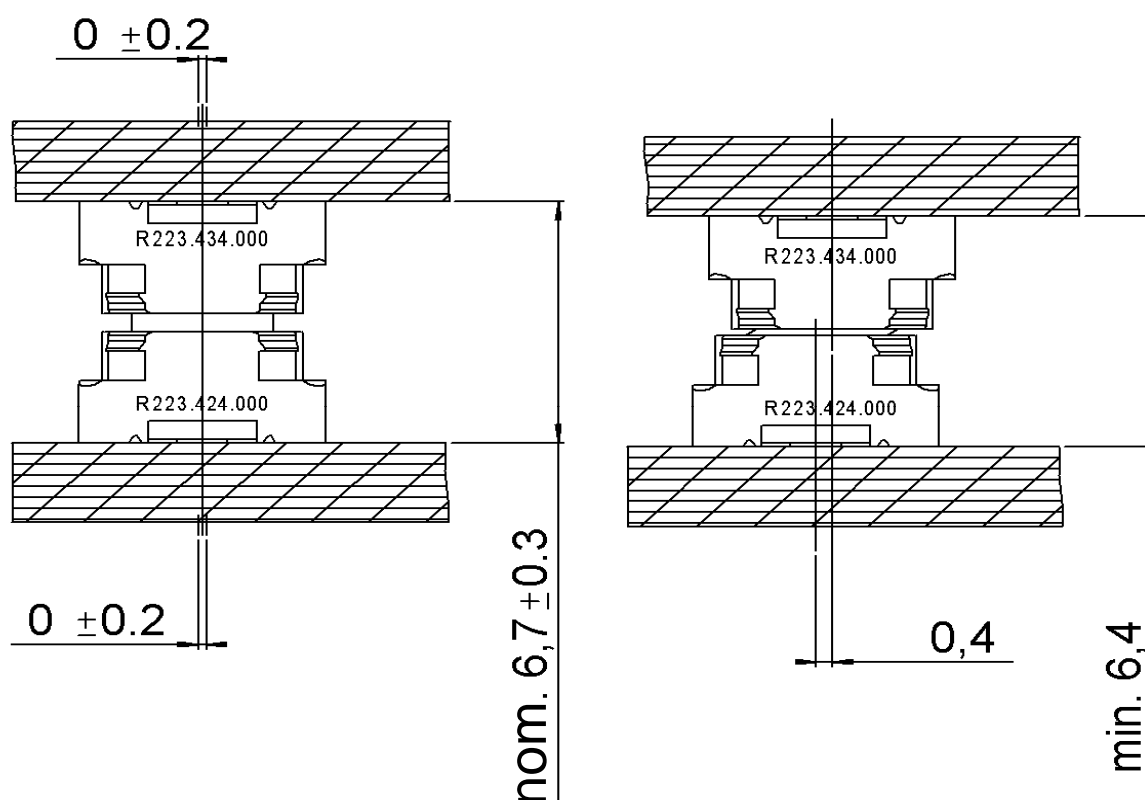


SMTJACK RECEPTACLE

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Series : MMBX

MMBX SERIES INFORMATIONS



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